

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A print assembly for a wide format printer, the print assembly comprising
 - a plurality of printhead modules, each of the plurality of printhead modules incorporating a printhead chip and an elongate carrier that is mountable on a support structure of the printer in an operative position with respect to a platen of the wide format printer and
 - the plurality of modules together incorporating at least fifty thousand nozzle arrangements, the printhead chip of each of the plurality of modules being positioned so that the printhead chips are capable of ejecting ink drops into a printing zone defined by the platen; and,
 - a flexible printed circuit board (PCB) that is also positioned on each of the plurality of printhead modules and that is configured to control operation of the printhead chips;
 - wherein each printhead chip is the product of an integrated circuit fabrication process, and each printhead chip includes a ~~water~~-wafer substrate and a CMOS drive circuitry layer positioned on the water substrate with the nozzle arrangements positioned on the ~~water~~-wafer substrate and the CMOS drive circuitry layer.
2. (Original) A print assembly as claimed in claim 1, in which the printhead chips together incorporate at least one hundred thousand nozzle arrangements.
3. (Original) A print assembly as claimed in claim 2, in which the printhead chips together incorporate at least two hundred thousand nozzle arrangements.
4. (Original) A print assembly as claimed in claim 3, which includes between forty and one hundred printhead chips positioned on the carrier.
5. – 6. (Cancelled).

7. (Previously Presented) A print assembly as claimed in claim 1, in which each nozzle arrangement is in the form of a micro electro-mechanical system that is electrically connected to the CMOS drive circuitry layer.

8. (Cancelled).

9. (Currently Amended) A print assembly as claimed in claim 1, in which the flexible printed circuit board (PCB) is connected between the CMOS drive circuitry layer of each printhead chip and [[the]]control circuitry.

10. (Previously Presented) A print assembly as claimed in claim 1, in which the printhead modules are configured so that the printhead chips are each positioned at a common angle of greater than zero degrees and less than ninety degrees with respect to a line extending a length of the printing zone, so that consecutive printhead chips overlap at their ends.

11. (Currently Amended) A wide format printer that comprises
a support structure;
a print assembly positioned on the support structure, the print assembly comprising
a plurality of printhead modules, each of the plurality of printhead modules incorporating a printhead chip and a carrier that is mounted in an operative position with respect to a platen of the wide format printer, the plurality of modules together incorporating at least fifty thousand nozzle arrangements, the printhead chip of each of the plurality of modules being positioned so that the printhead chips are capable of ejecting ink drops into a printing zone defined by the platen;
a flexible printed circuit board (PCB) that is also positioned on each of the plurality of modules and that is configured to control operation of the printhead chips; and,
a media feed mechanism positioned on the support structure to feed media into the print assembly;
wherein each printhead chip is the product of an integrated circuit fabrication process and each printhead chip includes a ~~water-wafer~~ substrate and a CMOS drive circuitry layer positioned on the ~~water-wafer~~ substrate with the nozzle arrangements positioned on the ~~water-wafer~~ substrate and the CMOS drive circuitry layer.